

Abstract

The present invention provides a micro hot embossing method, which can quick heat and cool, and uniformly pressing an object to be embossed. The object is laid on a mold and a sealing chamber is used to enclose the object and the mold. A high pressure fluid which has a temperature sufficient to heat the object to be thermoplastic is introduced into the chamber for heating and pressing the object. The present invention can quick heat and cool the object, emboss the object using a mold made of brittle material such as glass or silicon wafer, and uniformly press the object in a very large area.